

PCB Dimensions = 126.1 x 126.1 x 1.6 mm³
 Chip Dimensions = 99.9 x 99.9 mm²
 Active Area = 95.89 x 98.89 mm²

Drawn N.W Des. Appd.	Checked S.W	Date 17/11/2020	Tolerances Unless Stated	Outputs Via: Allextra 301-KAPM-060-10M Cables
			x.xx = ± 0.1 mm	Mating Connector: Cables from PCB crimped into retaining plate
			x.xxx = ± 0.01 mm	Testing Mating Connector: N/A
			Angular ± 0.25°	Substrate Number: A-5215 (A-4945) Potted Wire Bonds: No
			Material Thickness ± 10%	Substrate Material: 1.6 mm Thick Rogers Material
				Connector Orientation: Front connector on Front side, rear connector on rear side

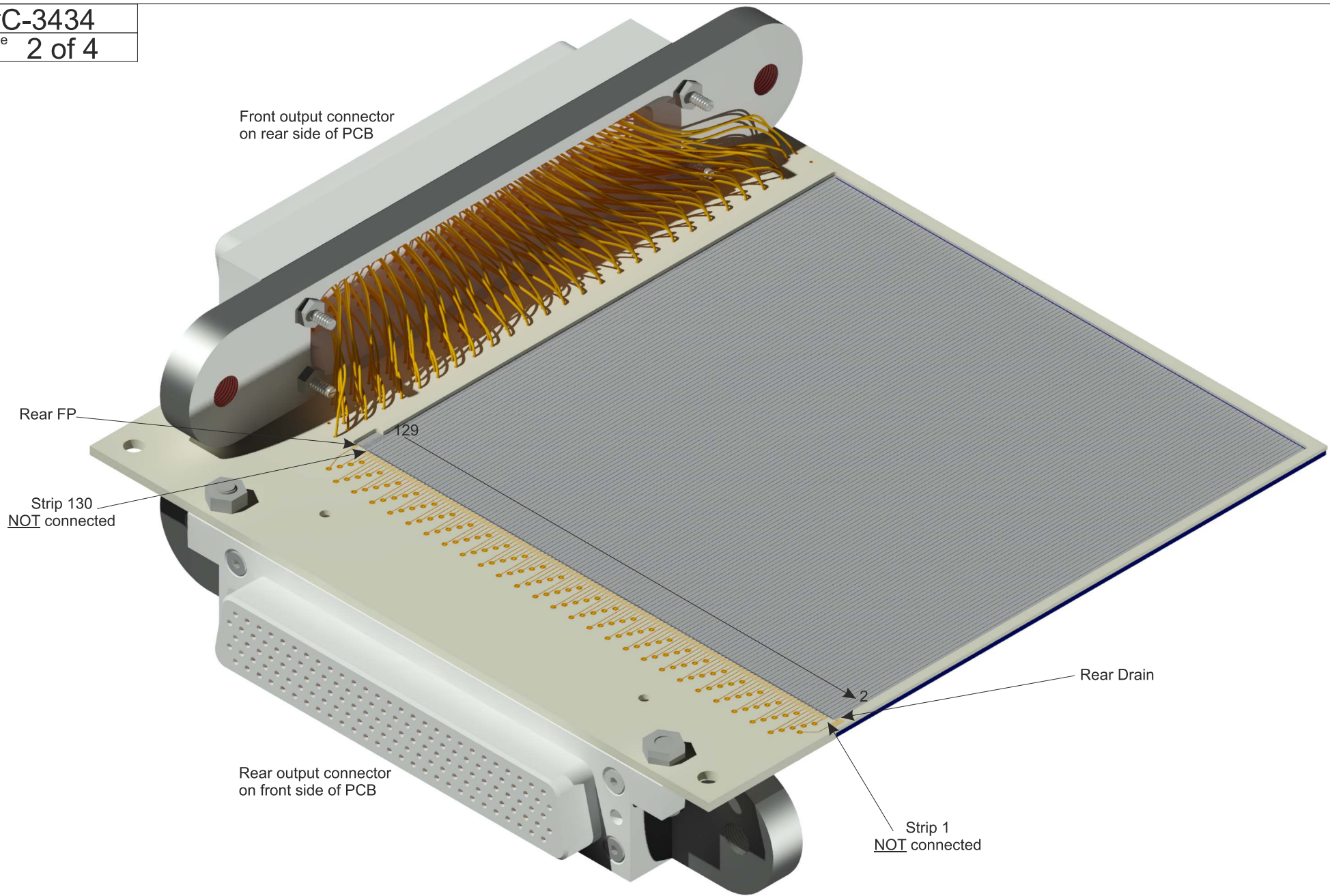
Title.
 TTT14 (DS) 2M/2M.
 3D Assembly.
 Front View.
 Revision 5
 Concept

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Scale N/A	Dims In. mm	Drg No C-3434
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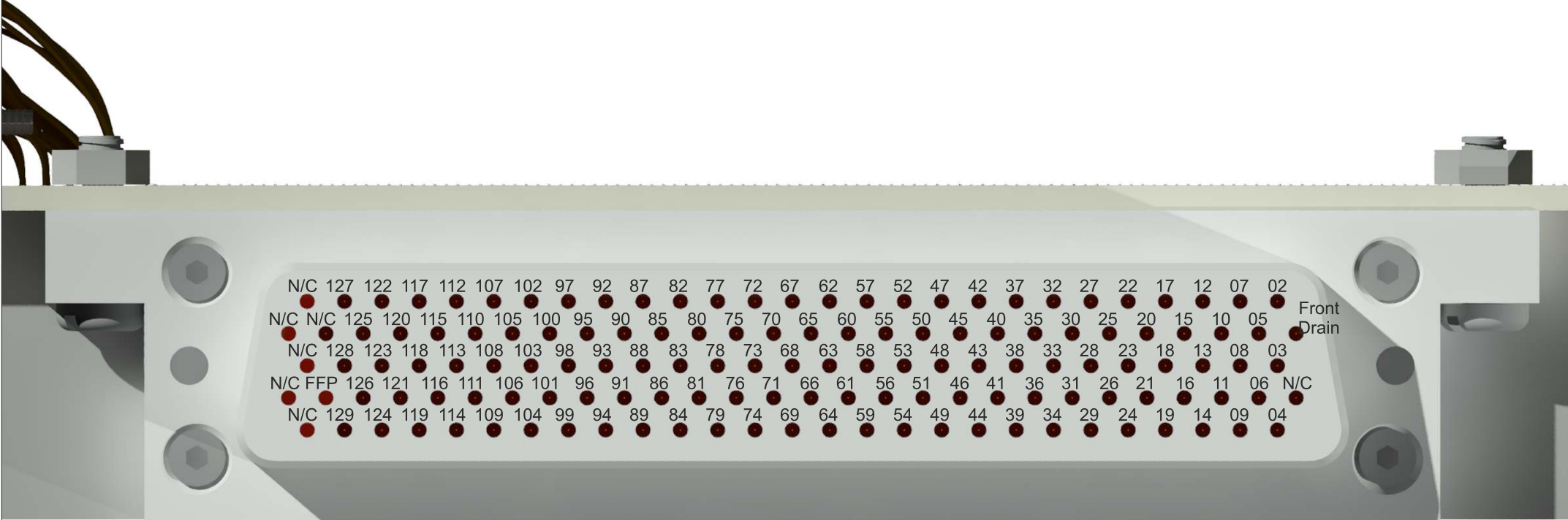


Drawn N.W Des. Appd.	Checked S.W	Date 17/11/2020	Tolerances Unless Stated		Outputs Via: Allcetra 301-KAPM-060-10M Cables	
			x.xx = ± 0.1 mm		Mating Connector: Cables from PCB crimped into retaining plate	
			x.xxx = ± 0.01 mm		Testing Mating Connector: N/A	
			Angular ± 0.25°		Substrate Number: A-5215 (A-4945)	Potted Wire Bonds: No
			Material Thickness ± 10%		Substrate Material: 1.6 mm Thick Rogers Material	
					Connector Orientation: Front connector on Front side, rear connector on rear side	

Title.

TTT14 (DS) 2M/2M.
3D Assembly.
Rear View
Revision 5.
Concept

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Scale N/A	Dims In. mm	Drg No C-3434



N/C = Not Connected
 FFP = Front Fieldplate

Drawn N.W Des. Appd.	Checked S.W	Date 17/11/2020	Tolerances Unless Stated		Outputs Via: Allcetra 301-KAPM-060-10M Cables
			x.xx = ± 0.1 mm		Mating Connector: Cables from PCB crimped into retaining plate
			x.xxx = ± 0.01 mm		Testing Mating Connector: N/A
			Angular ± 0.25°		Substrate Number: A-5215 (A-4945) Potted Wire Bonds: No
			Material Thickness ± 10%		Substrate Material: 1.6 mm Thick Rogers Material
			Connector Orientation: Front connector on Front side, rear connector on rear side		

Title.
TTT14 (DS) 2M/2M.
3D Assembly.
Front Output View.
Revision 5
Concept

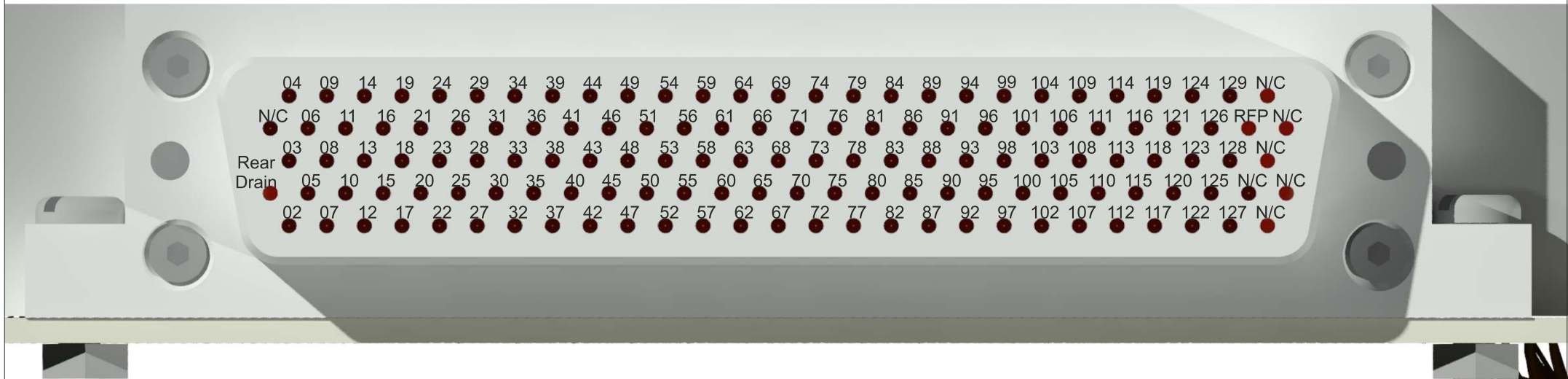


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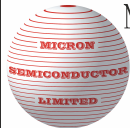
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Scale N/A	Dims In. mm	Drg No C-3434
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N/C = Not Connected
 RFP = Rear Fieldplate

Drawn N.W Des. Appd.	Checked S.W	Date 17/11/2020	Tolerances Unless Stated		Outputs Via: Allcetra 301-KAPM-060-10M Cables	Title. TTT14 (DS) 2M/2M. 3D Assembly. Rear Output View. Revision 5 Concept	 MICRON SEMICONDUCTOR LIMITED THIS DOCUMENT IS THE PROPERTY OF MICRON SEMICONDUCTOR LTD AND IS COMMERCIAL IN CONFIDENCE graphics@micronsemiconductor.co.uk	Scale N/A	Dims In. mm	Drg No C-3434	
			x.xx = ± 0.1 mm		Mating Connector: Cables from PCB crimped into retaining plate						
			x.xxx = ± 0.01 mm		Testing Mating Connector: N/A						
			Angular ± 0.25°		Substrate Number: A-5215 (A-4945)						Potted Wire Bonds: No
			Material Thickness ± 10%		Substrate Material: 1.6 mm Thick Rogers Material						
				Connector Orientation: Front connector on Front side, rear connector on rear side							